



SPECIFICATION

• Supplier : Samsung electro-mechanics • Part Number : CL10C2R2CB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 2.2pF, 50V, ± 0.25pF, C0G, 0603

A. Samsung Part Number

 CL
 10
 C
 2R2
 C
 B
 8
 N
 N
 N
 N
 C

 ①
 ②
 ③
 ④
 ⑤
 ⑥
 ⑦
 ⑧
 ⑨
 ⑩
 ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603	(inch code)	L: 1.60	±0.10 mm	W:	0.80	±0.10	mm
3	Dielectric	C0G		(8)	Inner electrode		Ni		
4	Capacitance	2.2	pF	•	Termination		Cu		
(5)	Capacitance	± 0.25	pF		Plating		Sn 10	0%	(Pb Free)
	tolerance			9	Product		Norma	al	
6	Rated Voltage	50	V	10	Special		Reser	ved for	future use
7	Thickness	0.80 ±0.	10 mm	11	Packaging		Cardb	oard T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	444 min						
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/ ℃)						
Adhesive Strength	No peeling shall be occur on the	500g⋅F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder					
	is to be soldered newly	235±5℃, 5±0.5sec.					
		2) SnAg3.0Cu0.5 solder					
		245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5 ℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)					
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs					
	within ±5% or ±0.5pF whichever is larger						
	Q: 222 min						
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F						
	Whichever is Smaller						
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q: 107.33 min						
	IR: 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature					
	Q: 222 min	1000+48/-0hrs					
	IR: 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25 °C					
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C					
		5 cycle test					

C. Recommended Soldering method : Reflow (Reflow Peak Temperature : 250±5 $^{\circ}$ C, 6sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.